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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
10/800,603	03/15/2004	Tomoo Yamasaki	CU-3637 RJS	1812
26530	7590	01/30/2006	EXAMINER	
LADAS & PARRY LLP 224 SOUTH MICHIGAN AVENUE SUITE 1600 CHICAGO, IL 60604			SANDVIK, BENJAMIN P	
			ART UNIT	PAPER NUMBER
			2826	

DATE MAILED: 01/30/2006

Please find below and/or attached an Office communication concerning this application or proceeding.

<b>Office Action Summary</b>	<b>Application No.</b> 10/800,603	<b>Applicant(s)</b> YAMASAKI ET AL.	
	<b>Examiner</b> Ben P. Sandvik	<b>Art Unit</b> 2826	

**– The MAILING DATE of this communication appears on the cover sheet with the correspondence address –  
Period for Reply**

A SHORTENED STATUTORY PERIOD FOR REPLY IS SET TO EXPIRE 3 MONTH(S) OR THIRTY (30) DAYS, WHICHEVER IS LONGER, FROM THE MAILING DATE OF THIS COMMUNICATION.

- Extensions of time may be available under the provisions of 37 CFR 1.136(a). In no event, however, may a reply be timely filed after SIX (6) MONTHS from the mailing date of this communication.
- If NO period for reply is specified above, the maximum statutory period will apply and will expire SIX (6) MONTHS from the mailing date of this communication.
- Failure to reply within the set or extended period for reply will, by statute, cause the application to become ABANDONED (35 U.S.C. § 133). Any reply received by the Office later than three months after the mailing date of this communication, even if timely filed, may reduce any earned patent term adjustment. See 37 CFR 1.704(b).

#### Status

- 1) ☒ Responsive to communication(s) filed on 14 November 2005.
- 2a) ☒ This action is **FINAL**.                      2b) ☐ This action is non-final.
- 3) ☐ Since this application is in condition for allowance except for formal matters, prosecution as to the merits is closed in accordance with the practice under *Ex parte Quayle*, 1935 C.D. 11, 453 O.G. 213.

#### Disposition of Claims

- 4) ☒ Claim(s) 1-19 is/are pending in the application.
- 4a) Of the above claim(s) \_\_\_\_\_ is/are withdrawn from consideration.
- 5) ☐ Claim(s) \_\_\_\_\_ is/are allowed.
- 6) ☒ Claim(s) 1-19 is/are rejected.
- 7) ☐ Claim(s) \_\_\_\_\_ is/are objected to.
- 8) ☐ Claim(s) \_\_\_\_\_ are subject to restriction and/or election requirement.

#### Application Papers

- 9) ☐ The specification is objected to by the Examiner.
- 10) ☐ The drawing(s) filed on \_\_\_\_\_ is/are: a) ☐ accepted or b) ☐ objected to by the Examiner.  
Applicant may not request that any objection to the drawing(s) be held in abeyance. See 37 CFR 1.85(a).  
Replacement drawing sheet(s) including the correction is required if the drawing(s) is objected to. See 37 CFR 1.121(d).
- 11) ☐ The oath or declaration is objected to by the Examiner. Note the attached Office Action or form PTO-152.

#### Priority under 35 U.S.C. § 119

- 12) ☐ Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f).
- a) ☐ All    b) ☐ Some \*    c) ☐ None of:
1. ☐ Certified copies of the priority documents have been received.
  2. ☐ Certified copies of the priority documents have been received in Application No. \_\_\_\_\_.
  3. ☐ Copies of the certified copies of the priority documents have been received in this National Stage application from the International Bureau (PCT Rule 17.2(a)).

\* See the attached detailed Office action for a list of the certified copies not received.

#### Attachment(s)

- |  |   |
|--|---|
| 1) <input type="checkbox"/> Notice of References Cited (PTO-892)   | 4) <input type="checkbox"/> Interview Summary (PTO-413)<br>Paper No(s)/Mail Date. _____ |
| 2) <input type="checkbox"/> Notice of Draftsperson's Patent Drawing Review (PTO-948)                                   | 5) <input type="checkbox"/> Notice of Informal Patent Application (PTO-152)             |
| 3) <input type="checkbox"/> Information Disclosure Statement(s) (PTO-1449 or PTO/SB/08)<br>Paper No(s)/Mail Date _____ | 6) <input type="checkbox"/> Other: _____  |

## **DETAILED ACTION**

### ***Response to Arguments***

Applicant's arguments filed on 11/14/2005 have been fully considered but they are not persuasive. The amended subject matter in claims 1, 7, 13, and 19 fails to overcome the previous art rejection, as detailed in the rejection below.

In response to applicant's argument that there is no suggestion to combine the references, the examiner recognizes that obviousness can only be established by combining or modifying the teachings of the prior art to produce the claimed invention where there is some teaching, suggestion, or motivation to do so found either in the references themselves or in the knowledge generally available to one of ordinary skill in the art. See *In re Fine*, 837 F.2d 1071, 5 USPQ2d 1596 (Fed. Cir. 1988) and *In re Jones*, 958 F.2d 347, 21 USPQ2d 1941 (Fed. Cir. 1992). In this case, the motivation to combine is found in Sweterlitsch (Col 2 Ln 31-40), which cites that the motivation to add a rim (240), referred to as the base in this rejection, is to enclosed the semiconductor chip. Also note that the applicant's arguments filed 11/14/05 are in reference to board 230 and base 100 of Sweterlitsch. The rejection being made refers to the rim 240 of Sweterlitsch as the "base" in the applicant's claims.

In response to applicant's argument that the examiner's conclusion of obviousness is based upon improper hindsight reasoning, it must be recognized that any judgment on obviousness is in a sense necessarily a reconstruction based upon hindsight reasoning. But so long as it takes into account only knowledge which was within the level of ordinary skill at the time the claimed invention was made, and does

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not include knowledge gleaned only from the applicant's disclosure, such a reconstruction is proper. See *In re McLaughlin*, 443 F.2d 1392, 170 USPQ 209 (CCPA 1971).

### ***Claim Rejections - 35 USC § 103***

The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

(a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negated by the manner in which the invention was made.

Claims 1-19 are rejected under 35 U.S.C. 103(a) as being unpatentable over Hale et al (U.S. Patent #6407929), in view of Sweterlitsch (U.S. Patent #6737742).

With respect to **claims 1-6**, Hale teaches a substrate body (Fig. 3, 302) having a wiring layer (Fig. 3, 306), and a reinforcing member provided in said substrate body and reinforcing said substrate body (Fig. 3, 310), wherein a part of the reinforcing member is exposed at a surface of the substrate body (Fig. 3, edge of 310 is exposed);

that the reinforcing member is a circuit board having a capacitor part that electrically connects the semiconductor element and the wiring layer (Fig. 10, 1004), as set forth in claim 2;

that the reinforcing member is an interposer having a via (Fig. 3, 312) that directly electrically connects the semiconductor element (Fig. 3, 314) and the wiring layer (Fig. 3, 306), as set forth in claim 4;

Hale does not teach a base formed by a material that is different from a material of said substrate body, supporting said substrate body, and having an opening forming portion where a semiconductor element is mounted, as set forth in claim 1; that the reinforcing member is arranged on the base via an abutting member made of a metal, as set forth in claims 3, 5, and 6.

Sweterlitsch teaches a base formed by a material that is different from a material of said substrate body, supporting said substrate body, and having an opening forming portion where a semiconductor element is mounted (Fig. 1, 240), as set forth in claim 1. It would have been obvious to one of ordinary skill in the art at the time the invention was made to provide a base supporting the substrate body of Hale wherein the reinforcing member is larger than the opening forming portion as taught by Sweterlitsch, and to arrange the reinforcing member on the base via an abutting member made of metal (Fig. 3, top layer of 302 in Hale) in order to protect the semiconductor element mounted therein.

With respect to **claims 7-12**, Hale teaches the manufacturing of a reinforcing member (Fig. 3, 310), forming a substrate body so that the reinforcing

member is provided in said substrate (Fig. 3, 302), said substrate body including a wiring layer (Fig. 3, 306), wherein a part of the reinforcing member is exposed at a surface of the substrate body (Fig. 3, edge of 310 is exposed);

the step of manufacturing the reinforcing member includes a step of forming a capacitor on a core member (Fig. 3, 308), as set forth in claim 8;

the step of manufacturing the reinforcing member includes a step of forming a via penetrating the core member (Fig. 3, via penetrating layer 304), as set forth in claim 9.

Hale does not teach arranging the reinforcing member on a base at a portion corresponding to an opening forming portion of the base, or forming the opening forming portion smaller than the reinforcing member, thereby exposing a part of the reinforcing member at the opening forming portion, as set forth in claim 1; or that the reinforcing member is arranged on the base via an abutting member made of metal, as set forth in claims 10, 11, and 12.

Sweterlitsch teaches a base arranged on a substrate with an opening forming portion that is smaller than the substrate and exposes the substrate, and is made of a material that is different from a material of the base (Fig. 1, 240), as set forth in claim 1. It would have been obvious to one of ordinary skill in the art at the time the invention was made to provide a base on the reinforcing member of Hale such that the opening forming portion is smaller than the reinforcing member and exposes the reinforcing member as taught by Sweterlitsch, and to

arranged the reinforcing member on the base via an abutting member made of metal (Fig. 3, top layer of 302 in Hale), in order to protect the semiconductor element therein.

With respect to **claims 13-18**, Hale teaches a substrate body having a wiring layer (Fig. 3, 306), and a reinforcing member provided in said substrate body and reinforcing said substrate body (Fig. 3, 310), and a semiconductor element mounted on the substrate (Fig. 3, 314), wherein a part of the reinforcing member is exposed at a surface of the substrate body (Fig. 3, edge of 310 is exposed);

that the reinforcing member is a circuit board having a capacitor part that electrically connects the semiconductor element and the wiring layer (Fig. 10, 1004), as set forth in claim 14;

that the reinforcing member is an interposer having a via (Fig. 3, 312) that directly electrically connects the semiconductor element (Fig. 3, 314) and the wiring layer (Fig. 3, 306), as set forth in claim 16;

Hale does not teach a base formed by a material that is different from a material of said substrate body, supporting said substrate body, and having an opening forming portion where a semiconductor element is mounted, as set forth in claim 1; that the reinforcing member is arranged on the base via an abutting member made of a metal, as set forth in claims 15, 17, and 18.

Sweterlitsch teaches a base formed by a material that is different from a material of said substrate body, supporting said substrate body, and having an opening forming portion where a semiconductor element is mounted (Fig. 1, 240), as set forth in claim 13. It would have been obvious to one of ordinary skill in the art at the time the invention was made to provide a base supporting the substrate body of Hale wherein the reinforcing member is larger than the opening forming portion as taught by Sweterlitsch, and to arrange the reinforcing member on the base via an abutting member made of metal (Fig. 3, top layer of 302 in Hale) in order to protect the semiconductor element mounted therein.

With respect to **claim 19**, Hale teaches a substrate body having a wiring layer (Fig. 10, 1008), and a reinforcing member embedded in said substrate body and reinforcing said substrate body (Fig. 10, middle layer), and a semiconductor element mounted on the substrate (Fig. 10, 1004), wherein a part of the reinforcing member is exposed at a surface of the substrate body (Fig. 10, edge of middle layer is exposed). Hale does not teach a base formed by a material that is different from a material of said substrate body, supporting said substrate body, and having an opening forming portion where a semiconductor element is mounted. Sweterlitsch teaches a base formed of a material that is different from a material of said substrate body, supporting said substrate body, and having an opening forming portion where a semiconductor element is mounted (Fig. 1, 240). It would have been obvious to one of ordinary skill in the art at the time the



invention was made to provide a base supporting said substrate body of Hale as taught by Sweterlitsch in order to protect the semiconductor element therein.

### ***Conclusion***

**THIS ACTION IS MADE FINAL.** Applicant is reminded of the extension of time policy as set forth in 37 CFR 1.136(a).

A shortened statutory period for reply to this final action is set to expire THREE MONTHS from the mailing date of this action. In the event a first reply is filed within TWO MONTHS of the mailing date of this final action and the advisory action is not mailed until after the end of the THREE-MONTH shortened statutory period, then the shortened statutory period will expire on the date the advisory action is mailed, and any extension fee pursuant to 37 CFR 1.136(a) will be calculated from the mailing date of the advisory action. In no event, however, will the statutory period for reply expire later than SIX MONTHS from the mailing date of this final action.

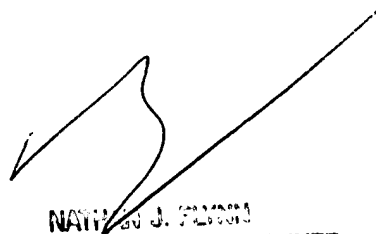
Any inquiry concerning this communication or earlier communications from the examiner should be directed to Ben P. Sandvik whose telephone number is (571) 272-8446. The examiner can normally be reached on Mon-Fri.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Nathan Flynn can be reached on (571) 272-1915. The fax phone number for the organization where this application or proceeding is assigned is 703-872-9306.

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Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see <http://pair-direct.uspto.gov>. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

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